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Application No.:  
10/065,003  
Docket NO.:8879-US-PA

**REMARKS****Present Status of the Application**

It is noted with great appreciation that the Examiner considers claims 7-13 as being allowed and claims 2 and 5 as being allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. The Office Action, under 35 U.S.C. § 102(b), rejected claims 1, 3-4 and 6 as being anticipated by Tachimatsu (JP 4-116849). The Office Action also rejected claim 3 under 35 U.S.C. 112, 2<sup>nd</sup> paragraph not particularly pointing out an distinctly claiming the subject matter which the applicant regards as his invention. Claim 1 and 3 have been amended to more accurately describe the invention. It is believed that no new matter is added by way of these amendments made to the claims or otherwise to the application.

Upon entry of the amendment in this response, claims 1-13 remain pending. After carefully considering the remarks set forth in this Office Action and the cited references, Applicants respectfully submitted that the presently pending claims are in condition for allowance. Reconsideration and withdrawal of the Examiner's rejection are requested.

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**Discussion of Office Action Rejections**

*Claim 3 is rejected under 35 U.S.C. 112, 2<sup>nd</sup> paragraph because there is insufficient antecedent basis for the limitation "the step of implanting ions into the substrate" in the claim.*

Claim 3 has been amended to depend on claim 2 to render 35 U.S.C. 112, 2<sup>nd</sup> paragraph rejection mooted. Reconsideration of the rejection is courteously requested.

*Claims 1, 3, 4, 6 are rejected under 35 U.S.C. § 102(b) as being anticipated by Tachimatsu (JP 4-116849).*

Applicants respectfully traverse the rejection as applied to the claims for at least the reason set forth below.

Claim 1 provides, among other things, "exposing the photoresist layer to light through a photomask, wherein the photomask has a plurality of repeated rectangular patterns with inwardly reduced corners having at least a straight cutting side thereon; developing the photoresist layer to form holes". Tachimatsu does not teach the above-mentioned limitations recited in claim 1. Tachimatsu, in contrast, teaches the corner parts are in a round shape. In a sense, the cutting side of Tachimatsu is a curve. Further, Tachimatsu fails to teach or suggest forming holes with the photoresist.

Additionally, the present invention is directed to obtain a bigger optical image contrast between the contacts for preventing an unnecessary peeling of the photoresist material between the contact, whereas Tachimatsu's invention is directed to prevent a

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generation of an inferior photomask when mounting because there is not acute angle in the contact part when handling the semiconductor elements by the vacuum pincette. Further, Tachimatsu's invention is applied to wafer dicing since the conventional method relies on a diamond blade to cut along the scribed line, and defects easily occur because of sharp corners. The present invention is applied to photolithography instead.

For at least *Tachimatsu* fails to disclose each element of the claim under consideration, Applicants submit that *Tachimatsu* does not anticipate the present invention, as recited in claim 1. Applicants, therefore, respectfully request that the rejection of claim 1 and claims 3-4, 6 dependent therefrom under 35 U.S.C. 102(b) be withdrawn.

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### CONCLUSION

For at least the foregoing reasons, it is believed that the presently pending claims 1-13 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Date :

*Sept 10, 2004*

Respectfully submitted,

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